

FEMTOCLOCK™ CRYSTAL-TO-LVCMOS/LVTTL FREQUENCY SYNTHESIZER

ICS840004-01

General Description



The ICS840004-01 is a 4 output LVCMOS/LVTTL Synthesizer optimized to generate Ethernet reference clock frequencies and is a member of the HiPerClocks™ family of high performance clock solutions from IDT. Using a 25MHz, 18pF parallel

resonant crystal, the following frequencies can be generated based on the 2 frequency select pins (F_SEL1:0): 156.25MHz, 125MHz, and 62.5MHz. The ICS840004-01 uses IDT's 3rd generation low phase noise VCO technology and can achieve 1ps or lower typical random rms phase jitter, easily meeting Ethernet jitter requirements. The ICS840004-01 is packaged in a small 20-pin TSSOP package.

Features

- Four single-ended LVCMOS/LVTTL outputs 17Ω typical output impedance
- Selectable crystal oscillator interface or single-ended input
- Output frequency range: 56MHz 175MHz
- VCO range: 560MHz 700MHz
- RMS phase jitter at 156.25MHz (1.875MHz 20MHz): 0.52ps (typical)

Phase Noise:

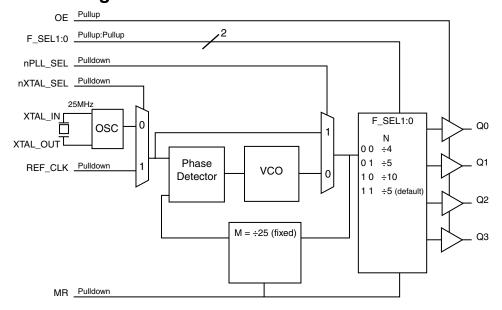
| Noise Power |
|---------------|
| -94.9 dBc/Hz |
| -119.6 dBc/Hz |
| -128.9 dBc/Hz |
| -129.2 dBc/Hz |
| |

- Full 3.3V or mixed 3.3V core/2.5V output supply modes
- 0°C to 70°C ambient operating temperature
- Available in both standard (RoHS 5) and lead-free (RoHS 6) packages

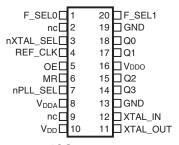
Frequency Select Function Table for Ethernet Frequencies

| | | Input | | | |
|--------|--------|--------------|--------------|-----------------|---|
| F_SEL1 | F_SEL0 | M Div. Value | N Div. Value | M/N Ratio Value | Output Frequency (MHz), (25MHz Reference) |
| 0 | 0 | 25 | 4 | 6.25 | 156.25 |
| 0 | 1 | 25 | 5 | 5 | 125 |
| 1 | 0 | 25 | 10 | 2.5 | 62.5 |
| 1 | 1 | 25 | 5 | 5 | 125 (default) |

Block Diagram



Pin Assignment



ICS840004-01

20-Lead TSSOP 6.5mm x 4.4mm x 0.925mm package body G Package Top View

Table 1. Pin Descriptions

| Number | Name | Ty | /pe | Description |
|----------------|----------------------|--------|----------|---|
| 1, 20 | F_SEL0, F_SEL1 | Input | Pullup | Frequency select pins. LVCMOS/LVTTL interface levels. |
| 2, 9 | nc | Unused | | No connect. |
| 3 | nXTAL_SEL | Input | Pulldown | Selects betweent he crystal or REF_CLK inputs as the PLL reference source. When HIGH, selects REF_CLK. When LOW, selects XTAL inputs. LVCMOS/LVTTL interface levels. |
| 4 | REF_CLK | Input | Pulldown | Single-ended reference clock input. LVCMOS/LVTTL interface levels. |
| 5 | OE | Input | Pullup | Output enable pin. When HIGH, the outputs are active. When LOW, the outputs are in a high impedance state. LVCMOS/LVTTL interface levels. |
| 6 | MR | Input | Pulldown | Active HIGH master reset. When logic HIGH, the internal dividers are reset causing the outputs to go low. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS/LVTTL interface levels. |
| 7 | nPLL_SEL | Input | Pulldown | PLL bypass. When LOW, the output is driven from the VCO output. When HIGH, the PLL is bypassed and the output frequency = reference clock frequency/N output divider. LVCMOS/LVTTL interface levels. |
| 8 | V_{DDA} | Power | | Analog supply pin. |
| 10 | V_{DD} | Power | | Core supply pin. |
| 11, 12 | XTAL_OUT, XTAL_IN | Input | | Crystal oscillator interface. XTAL_IN is the input. XTAL_OUT is the output. |
| 13, 19 | GND | Power | | Power supply ground. |
| 14, 15, 17, 18 | Q3, Q2, Q1, Q0 | Output | | Single-ended clock outputs. 17 Ω typical output impedance. LVCMOS/ LVTTL interface levels. |
| 16 | V_{DDO} | Power | | Output supply pin. |

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

Table 2. Pin Characteristics

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|-----------------------|-------------------------------|----------------------------|---------|---------|---------|-------|
| C _{IN} | Input Capacitance | | | 4 | | pF |
| C _{PD} | Power Dissipation Capacitance | | | 8 | | pF |
| R _{PULLUP} | Input Pullup Resistor | | | 51 | | kΩ |
| R _{PULLDOWN} | Input Pulldown Resistor | | | 51 | | kΩ |
| D | Output Impodance | $V_{DDO} = 3.3V \pm 5\%$ | | 17 | | Ω |
| R _{OUT} | Output Impedance | V _{DDO} = 2.5V±5% | | 21 | | Ω |

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

| Item | Rating |
|--|----------------------------------|
| Supply Voltage, V _{DD} | 4.6V |
| Inputs, V _I | -0.5V to V _{DD} + 0.5V |
| Outputs, V _O | -0.5V to V _{DDO} + 0.5V |
| Package Thermal Impedance, θ_{JA} | 73.2°C/W (0 lfpm) |
| Storage Temperature, T _{STG} | -65°C to 150°C |

DC Electrical Characteristics

Table 3A. Power Supply DC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$, $T_A = 0^{\circ}C$ to $70^{\circ}C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|------------------|-----------------------|-----------------|---------|---------|---------|-------|
| V_{DD} | Core Supply Voltage | | 3.135 | 3.3 | 3.465 | ٧ |
| V_{DDA} | Analog Supply Voltage | | 3.135 | 3.3 | 3.465 | ٧ |
| V | Output Cumply Voltage | | 3.135 | 3.3 | 3.465 | ٧ |
| V_{DDO} | Output Supply Voltage | | 2.375 | 2.5 | 2.625 | ٧ |
| I _{DD} | Power Supply Current | | | | 100 | mA |
| I _{DDA} | Analog Supply Current | | | | 12 | mA |
| I _{DDO} | Output Supply Current | | | | 10 | mA |

Table 3B. LVCMOS/LVTTL DC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$, $T_A = 0^{\circ}C$ to $70^{\circ}C$

| Symbol | Parameter | | Test Conditions | Minimum | Typical | Maximum | Units |
|-----------------|-----------------------------|--|--|---------|---------|-----------------------|-------|
| V _{IH} | Input High Volta | ge | V _{DD} = 3.465V | 2 | | V _{DD} + 0.3 | V |
| V_{IL} | Input Low Voltage | ge | V _{DD} = 3.465V | -0.3 | | 0.8 | V |
| I _{IH} | Input High Current | nXTAL_SEL, nPLL_SEL, REF_CLK, MR | V _{DD} = V _{IN} = 3.465V | | | 150 | μA |
| | | OE, F_SEL[0:1] | $V_{DD} = V_{IN} = 3.465V$ | | | 5 | μΑ |
| I _{IL} | Input Low Current | nXTAL_SEL, nPLL_SEL, REF_CLK, MR | V _{DD} = 3.465V, V _{IN} = 0V | -5 | | | μΑ |
| | | OE, F_SEL[0:1] | $V_{DD} = 3.465V, V_{IN} = 0V$ | -150 | | | μA |
| V | Output High Vol | taga: NOTE 1 | $V_{DDO} = 3.3V \pm 5\%$ | 2.6 | | | V |
| V _{OH} | Output High Voltage; NOTE 1 | | $V_{DDO} = 2.5V \pm 5\%$ | 1.8 | | | V |
| V _{OL} | Output Low Volt | age; NOTE 1 | $V_{DDO} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$ | | | 0.5 | V |

NOTE 1: Outputs terminated with 50Ω to $V_{DDO}/2$. See Parameter Measurement Information section. Load Test Circuit diagrams.

Table 4. Crystal Characteristics

| Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|------------------------------------|-----------------|---------|------------|---------|-------|
| Mode of Oscillation | | | Fundamenta | ıl | |
| Frequency | | | 25 | | MHz |
| Equivalent Series Resistance (ESR) | | | | 50 | Ω |
| Shunt Capacitance | | | | 7 | pF |
| Drive Level | | | | 1 | mW |

AC Electrical Characteristics

Table 5A. AC Characteristics, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$, $T_A = 0$ °C to 70°C

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|---------------------------------|--------------------------------------|---|---------|---------|---------|-------|
| | | F_SEL[1:0] = 00 | 140 | 156.25 | 175 | MHz |
| f _{out} | Output Frequency | F_SEL[1:0] = 01 or 11 | 112 | 125 | 140 | MHz |
| | | F_SEL[1:0] = 10 | 56 | 62.5 | 70 | MHz |
| tsk(o) | Output Skew: NOTE 1, 2 | | | | 60 | MHz |
| | | 156.25MHz, Integration Range: 1.875MHz – 20MHz | | 0.52 | | ps |
| tjit(Ø) | RMS Phase Jitter (Random); NOTE 3 | 125MHz, Integration Range: 1.875MHz – 20MHz | | 0.65 | | ps |
| | | 62.5MHz, Integration Range: 1.875MHz – 20MHz | | 0.55 | | ps |
| t _R / t _F | Output Rise/Fall Time | 20% to 80% | 200 | | 700 | ps |
| odc | Output Duty Cycle | F_SEL[1:0] = 00, 01 or 11 | 43 | | 57 | % |
| ouc | Output Duty Oycle | F_SEL[1:0] = 10 | 49 | | 51 | % |

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE 1: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V_{DDO}/2.

NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 3: Please refer to the Phase Noise Plots.

Table 5B. AC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 2.5V \pm 5\%$, $T_A = 0$ °C to 70°C

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|---------------------------------|--------------------------------------|---|---------|---------|---------|-------|
| | | F_SEL[1:0] = 00 | 140 | 156.25 | 175 | MHz |
| f _{out} | Output Frequency | F_SEL[1:0] = 01 or 11 | 112 | 125 | 140 | MHz |
| | | F_SEL[1:0] = 10 | 56 | 62.5 | 70 | MHz |
| tsk(o) | Output Skew: NOTE 1, 2 | | | | 60 | MHz |
| | | 156.25MHz, Integration Range: 1.875MHz – 20MHz | | 0.48 | | ps |
| THT((/)) | RMS Phase Jitter (Random); NOTE 3 | 125MHz, Integration Range: 1.875MHz – 20MHz | | 0.59 | | ps |
| | | 62.5MHz, Integration Range: 1.875MHz – 20MHz | | 0.53 | | ps |
| t _R / t _F | Output Rise/Fall Time | 20% to 80% | 200 | | 700 | ps |
| odc | Output Duty Cyclo | F_SEL[1:0] = 00, 01 or 11 | 43 | | 57 | % |
| ouc | Output Duty Cycle | F_SEL[1:0] = 10 | 49 | | 51 | % |

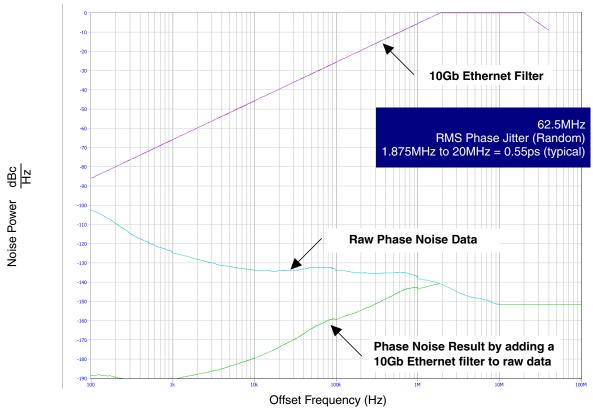
NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE 1: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V_{DDO}/2.

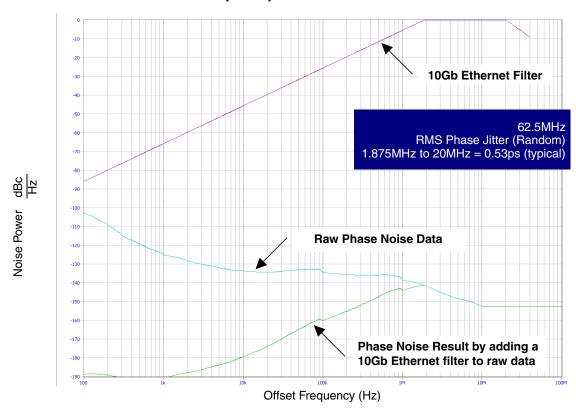
NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 3: Please refer to the Phase Noise Plots.

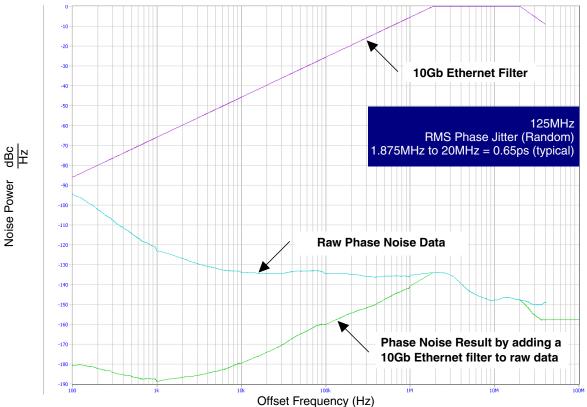
Typical Phase Noise at 62.5MHz (3.3V)



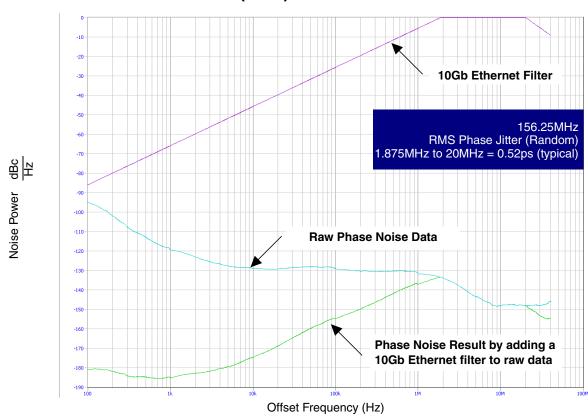
Typical Phase Noise at 62.5MHz (2.5V)



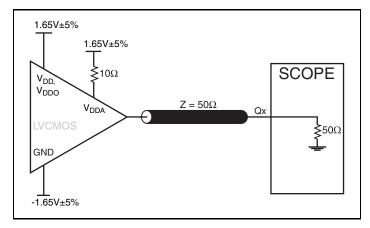
Typical Phase Noise at 125MHz (3.3V)



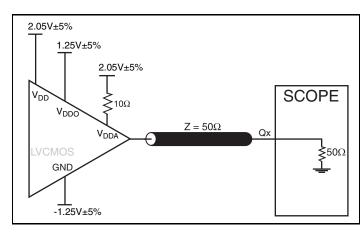
Typical Phase Noise at 156.25MHz (3.3V)



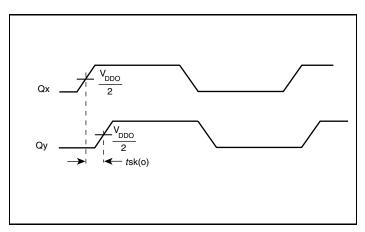
Parameter Measurement Information



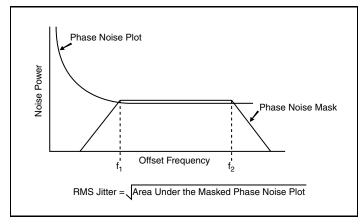
3.3V Core/3.3V LVCMOS Output Load AC Test Circuit



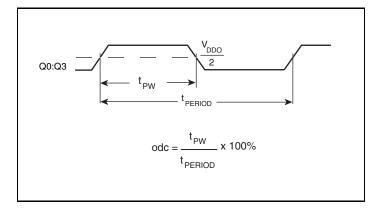
3.3V Core/2.5V LVCMOS Output Load AC Test Circuit



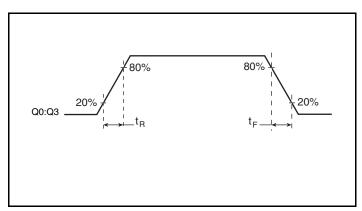
Output Skew



RMS Phase Jitter



Output Duty Cycle Pulse Width/Period



Output Rise/Fall Time

Application Information

Recommendations for Unused Input and Output Pins

Inputs:

Crystal Inputs

For applications not requiring the use of the crystal oscillator input, both XTAL_IN and XTAL_OUT can be left floating. Though not required, but for additional protection, a $1 \mbox{k}\Omega$ resistor can be tied from XTAL_IN to ground.

REF_CLK Input

For applications not requiring the use of the reference clock, it can be left floating. Though not required, but for additional protection, a $1k\Omega$ resistor can be tied from the REF_CLK to ground.

LVCMOS Control Pins

All control pins have internal pull-downs; additional resistance is not required but can be added for additional protection. A 1k $\!\Omega$ resistor can be used.

Outputs:

LVCMOS Outputs

All unused LVCMOS outputs can be left floating. We recommend that there is no trace attached.

Power Supply Filtering Technique

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. To achieve optimum jitter performance, power supply isolation is required. The ICS840004-01 provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL. $V_{DD_{\rm i}}$ V_{DDA} and V_{DDO} should be individually connected to the power supply plane through vias, and 0.01µF bypass capacitors should be used for each pin. Figure 1 illustrates this for a generic V_{DD} pin and also shows that V_{DDA} requires that an additional 10Ω resistor along with a $10\mu F$ bypass capacitor be connected to the V_{DDA} pin.

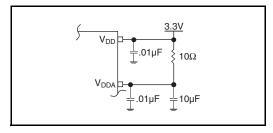


Figure 1. Power Supply Filtering

Crystal Input Interface

The ICS840004-01 has been characterized with 18pF parallel resonant crystals. The capacitor values shown in *Figure 2* below were determined using a 25MHz, 18pF parallel resonant crystal and were chosen to minimize the ppm error.

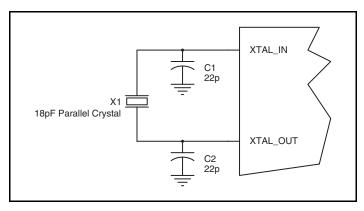


Figure 2. Crystal Input Interface

LVCMOS to XTAL Interface

The XTAL_IN input can accept a single-ended LVCMOS signal through an AC coupling capacitor. A general interface diagram is shown in *Figure 3*. The XTAL_OUT pin can be left floating. The input edge rate can be as slow as 10ns. For LVCMOS inputs, it is recommended that the amplitude be reduced from full swing to half swing in order to prevent signal interference with the power rail and to reduce noise. This configuration requires that the output

impedance of the driver (Ro) plus the series resistance (Rs) equals the transmission line impedance. In addition, matched termination at the crystal input will attenuate the signal in half. This can be done in one of two ways. First, R1 and R2 in parallel should equal the transmission line impedance. For most 50Ω applications, R1 and R2 can be 100Ω . This can also be accomplished by removing R1 and making R2 50Ω .

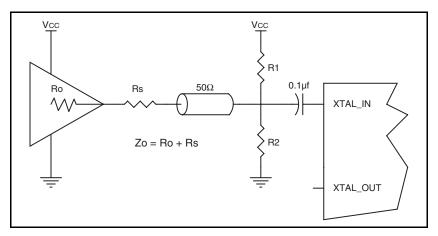


Figure 3. General Diagram for LVCMOS Driver to XTAL Input Interface

Schematic Example

Figure 4 shows a schematic example of the ICS840004-01. An example of LVCMOS termination is shown in this schematic. Additional LVCMOS termination approaches are shown in the LVCMOS Termination Application Note. In this example, an 18pF parallel resonant 25MHz crystal is used. The C1= 22pF and

C2 = 22pF are recommended for frequency accuracy. For different board layouts, the C1 and C2 may be slightly adjusted for optimizing frequency accuracy. $1k\Omega$ pullup or pulldown resistors can be used for the logic control input pins.

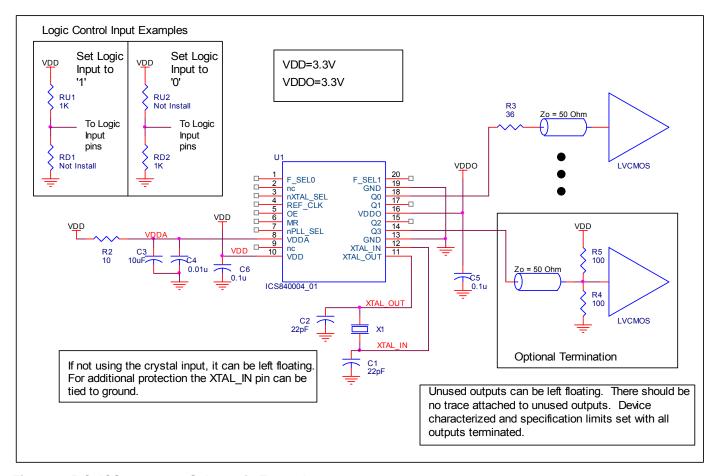


Figure 4. P.C. ICS840004-01 Schematic Example

Reliability Information

Table 6. θ_{JA} vs. Air Flow Table for a 20 Lead TSSOP

| | θ_{JA} by Velocity | | | |
|--|---------------------------|----------|----------|--|
| Linear Feet per Minute | 0 | 200 | 500 | |
| Single-Layer PCB, JEDEC Standard Test Boards | 114.5°C/W | 98.0°C/W | 88.0°C/W | |
| Multi-Layer PCB, JEDEC Standard Test Boards | 73.2°C/W | 66.6°C/W | 63.5°C/W | |
| NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs. | | | | |

Transistor Count

The transistor count for ICS840004-01: 3796

Package Outline and Package Dimensions

Package Outline - G Suffix for 20 Lead TSSOP

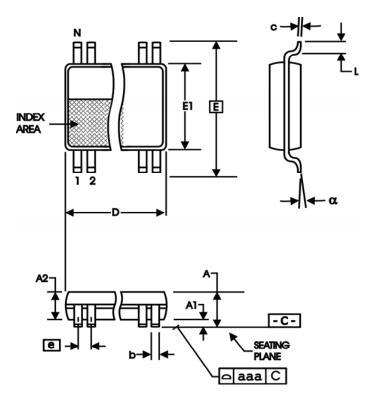


Table 7. Package Dimensions for 20 Lead TSSOP

| All Dimensions in Millimeters | | | | |
|-------------------------------|---------|---------|--|--|
| Symbol | Minimum | Maximum | | |
| N | 2 | 20 | | |
| Α | | 1.20 | | |
| A 1 | 0.05 | 0.15 | | |
| A2 | 0.80 | 1.05 | | |
| b | 0.19 | 0.30 | | |
| С | 0.09 | 0.20 | | |
| D | 6.40 | 6.60 | | |
| E | 6.40 | Basic | | |
| E1 | 4.30 | 4.50 | | |
| е | 0.65 | Basic | | |
| L | 0.45 | 0.75 | | |
| α | 0° | 8° | | |
| aaa | | 0.10 | | |

Reference Document: JEDEC Publication 95, MO-153

Ordering Information

Table 8. Ordering Information

| Part/Order Number | Marking | Package | Shipping Packaging | Temperature |
|-------------------|--------------|---------------------------|--------------------|-------------|
| 840004AG-01 | ICS840004A01 | 20 Lead TSSOP | Tube | 0°C to 70°C |
| 840004AG-01T | ICS840004A01 | 20 Lead TSSOP | 2500 Tape & Reel | 0°C to 70°C |
| 840004AG-01LF | ICS40004A01L | 20 Lead "Lead-Free" TSSOP | Tube | 0°C to 70°C |
| 840004AG-01LFT | ICS40004A01L | 20 Lead "Lead-Free" TSSOP | 2500 Tape & Reel | 0°C to 70°C |

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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Revision History Sheet

| Rev | Table | Page | Description of Change | Date |
|-----|----------|-------|---|----------|
| В | T5A, T5B | 4 - 5 | AC Characteristics Tables - revised Test Conditions for Output Duty Cycle. Updated format throughout datasheet. | 10/30/08 |
| | | | | |

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